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FORM PT0-1390 (Rev. 11/00) (adapted)

U.S. DEPARTMENT OF COMMERCE — PATENT AND TRADEMARK OFFICE		ATTORNEY DOCKET NUMBER
TRANSMITTAL LETTER TO THE UNITED STATES		MP1705-US3
DESIGNATED/ELECTED OFFICE (DO/EO/US)		US Appl'n No. (if known, 37 CFR 1.5)
CONCERNING A FILING UNDER 35 U.S.C. 371		10/088253 As yet unknown
INTERNATIONAL APPL'N NO.	INTERNATIONAL FILING DATE	PRIORITY DATE CLAIMED
PCT/US00/25118	13 September 2000 (13.09.00)	14 September 1999 (14.09.99)

Applicant herewith submits to the United States Designated/Elected Office (DO/EO/US) the following items and other information:

1. ☒ This is a FIRST submission of items concerning a filing under 35 U.S.C. 371.
2. ☐ This is a SECOND or SUBSEQUENT submission of items concerning a filing under 35 U.S.C. 371.
3. ☒ This express request to begin national examination procedures (35 U.S.C. 371(f)) at any time rather than delay examination until the expiration of the applicable time limit set in 35 U.S.C. 371(b) and PCT Articles 22 and 39(1).
4. ☒ A proper Demand for International Preliminary Examination was made by the 19th month from the earliest claimed priority date.
5. ☒ A copy of the International Application as filed (35 U.S.C. 371(c)(2)).
 - a. ☒ is transmitted herewith (required only if not transmitted by the International Bureau).
 - b. ☐ has been transmitted by the International Bureau.
 - c. ☐ is not required, as the application was filed in the United States Receiving Office (RO/US).
6. ☐ A translation of the International Application into English (35 U.S.C. 371(c)(2)).
7. ☒ Amendments to the claims of the International Application under PCT Article 19 (35 U.S.C. 371(c)(3)).
 - a. ☐ are transmitted herewith (required only if not transmitted by the International Bureau).
 - b. ☐ have been transmitted by the International Bureau.
 - c. ☒ have not been made and will not be made.
8. ☐ A translation of the amendments to the claims under PCT Article 19 (35 U.S.C. 371(c)(3)).
9. ☐ An oath or declaration of the inventor(s) (35 U.S.C. 371(c)(4)).
10. ☐ A translation of the annexes to the International Preliminary Examination Report under PCT Article 36 (35 U.S.C. 371(c)(5)).

Items 11. to 18. below concern document(s) or information included:

11. ☐ An Information Disclosure Statement under 37 CFR 1.97 and 1.98.
12. ☐ An assignment document for recording. A separate cover sheet in compliance with 37 CFR 3.28 and 3.31 is included.
13. ☒ A FIRST preliminary amendment.
☐ A SECOND or SUBSEQUENT preliminary amendment.
14. ☐ A substitute specification.
15. ☐ A change of power of attorney and/or address letter.
16. ☐ Formal drawings
17. ☒ Return receipt postcard (MPEP §503) (specifically itemized).
18. ☐ Other items of information:

EXPRESS MAIL CERTIFICATION UNDER 37 CFR 1.10

I hereby certify that this paper or fee is being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 in an envelope addressed to the Commissioner for Patents, Washington, DC 20231, on the date indicated below:

Date of deposit: March 14, 2002 Express Mail mailing label no. EF278785430US
 Name (printed): Michael Mitchell Signature: _____

JG13 Rec'd PCT/PTO 14 MAR 2002

U.S. APPL'N NO. (if known, 37 CFR 1.5) As yet unknown 13/000253	INT'L APPL'N NO. PCT/US00/25118	ATTORNEY DOCKET NO. MP1705-US3
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19. <input checked="" type="checkbox"/> The following fees are submitted: BASIC NATIONAL FEE (37 CFR 1.492(a)(1)-(5): Neither international preliminary examination fee (37 CFR 1.482) nor international search fee (37 CFR 1.445(a)(2)) paid to USPTO and international Search Report not prepared by the EPO or JPO \$1040.00 International preliminary examination fee (37 CFR 1.482) not paid to USPTO but International Search Report prepared by the EPO or JPO \$890.00 International preliminary examination fee (37 CFR 1.482) not paid to USPTO but international search fee paid to USPTO (37 CFR 1.445(a)(2)) \$740.00 International preliminary examination fee (37 CFR 1.482) paid to USPTO but all claims did not satisfy provisions of PCT Article 33(1)-(4) \$710.00 International preliminary examination fee (37 CFR 1.482) paid to USPTO and all claims satisfied provisions of PCT Article 33(1)-(4) \$100.00 ENTER APPROPRIATE BASIC FEE AMOUNT = \$ 890.00				CALCULATIONS		PTO USE ONLY	
Surcharge of \$130.00 for furnishing oath or declaration later than <input type="checkbox"/> 20 <input type="checkbox"/> 30 months from the earliest claimed priority date (37 (CFR 1.492(e))).				\$ 0.00			
CLAIMS	NUMBER FILED	NUMBER EXTRA	RATE				
Total claims	3 - 20 =		x \$18.00	\$ 0.00			
Ind. claims	2 - 3 =		x \$84.00	\$ 0.00			
MULTIPLE DEPENDENT CLAIM(s) (if applicable)			+ \$280.00	\$ 0.00			
TOTAL OF ABOVE CALCULATIONS =				\$ 890.00			
Reduction of 1/2 for filing by small entity, if applicable. A Small Entity Statement must also be filed (Note 37 CFR 1.9, 1.27, 1.28) -				\$ 0.00			
SUBTOTAL =				\$ 890.00			
Processing fee of \$130.00 for furnishing the English translation later than <input type="checkbox"/> 20 <input type="checkbox"/> 30 months from the earliest claimed priority date (37 (CFR 1.492(f))).				\$ 0.00			
TOTAL NATIONAL FEE =				\$ 890.00			
Fee for recording the enclosed assignment (37 CFR 1.21(h)). The assignment must be accompanied by an appropriate cover sheet (37 CFR 3.28, 3.31). \$40.00 per property +				\$ 0.00			
TOTAL FEES ENCLOSED =				\$ 0.00			
Amount to be:				refunded:		\$	
				charged:		\$	

- a. ☐ A check in the amount of \$ **0.00** to cover the above fees is enclosed.
- b. ☒ Please charge my Deposit Acct. No. **18-0560 (Raychem Corporation)** in the amount of \$ **890.00** to cover the above fees. A duplicate copy of this sheet is enclosed.
- c. ☒ The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to Deposit Acct. No. **18-0560 (Raychem Corporation)**. A duplicate copy of this sheet is enclosed.

NOTE: Where an appropriate time limit under 37 CFR 1.494 or 1.495 has not been met, a petition to revive (37 CFR 1.137(a) or (b)) must be filed and granted to restore the application to pending status.

SEND ALL CORRESPONDENCE TO:

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Intellectual Property Law Department
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PATENT APPLICATION
MP1705-US3

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of) Group Art Unit: Unknown
)
HETHERTON ET AL.) Examiner: Unknown
)
Application No.: Unknown) TYCO ELECTRONICS CORPORATION
(International Application No. PCT/US00/25118)) 307 Constitution Drive
) Menlo Park, CA 94025
Filed: Herewith)
(International Filing Date: 13 September 2000))
)
For: ELECTRICAL DEVICES AND PROCESS) March 14, 2002
FOR MAKING SUCH DEVICES)

PRELIMINARY AMENDMENT

Box PCT
United States Receiving Office (RO/US)
Commissioner for Patents
Washington, DC 20231

Sir:

This is a Preliminary Amendment to an international application, Application No. PCT/US00/25118, which is entering the national stage of prosecution in the United States. Before examining this application and calculating the filing fee, please amend this application as set out in the Amendments and Remarks below. Please charge any necessary fees or credit any overpayment to deposit account number 18-0560.

AMENDMENTS

Please amend this application as follows.

EXPRESS MAIL CERTIFICATION UNDER 37 CFR §1.10

I hereby certify that this paper or fee is being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR §1.10 on the date indicated below and is addressed to the Commissioner for Patents, Washington, DC 20231.

Express Mail mailing label no. EF278785430US Date of Deposit March 14, 2002

Typed/printed name Michael Mitchell Signature _____

In the Specification

Please add the following two paragraphs before the paragraph beginning at page 1, line 3 of the specification ("Background of the Invention").

Reference to Related Applications

This application is the national stage of International Application No. PCT/US00/25118, filed September 13, 2000, which is a continuation-in-part of U.S. Application No. 09/395,869, filed September 14, 1999. The disclosure of each of these applications is incorporated herein by reference.

Please replace the paragraph beginning at page 20, line 19 by the following paragraph.

Figure 6 shows in cross-section a composite device 2 as in Figure 5 soldered to traces 41 and 43 on an insulating substrate 9.

Please replace the paragraph beginning at page 22, line 8 by the following paragraph.

Figure 21 illustrates a composite device which has only one internal electrode 16, formed from a stack with only one internal conductive surface. A laminar element 17 is combined with the laminar element 76. The laminar elements can be pressed together to form a bond, so that no third laminar element is required to secure the laminar elements together. For example, 17 can comprise a PTC element and 76 can comprise a dielectric substrate with adhesive properties.

Please replace the paragraph beginning at page 24, line 6 by the following paragraph.

One surface of one foil layer of each of two laminates was patterned using an etching technique in which the surface was first coated with an etch resist, then imaged in a desired pattern. The etch resist was developed and etching was accomplished using cupric chloride before the resist was stripped away. These same foil layers were patterned to define the periphery of the individual devices and the residual conductive members. In addition, the outer edges of the metal foil on the laminate were etched to provide an alternating cross

directional pattern around the perimeter, as shown in Figure 2. Paths providing electrical continuity were utilized during the subsequent electrolytic plating of Sn/Pb.

Please replace the two paragraphs beginning at page 26, line 11 by the following two paragraphs.

A stacked assembly in accordance with Figure 26 was prepared by the following method. One laminate having a thickness of about 0.198 mm (0.0078 inch) was prepared by attaching a nickel/copper foil having a thickness of about 0.0356 mm (0.0014 inch) to both major sides of a 0.127 mm (0.005 inch)-thick sheet of conductive polymer. The conductive polymer was prepared by mixing about 37% by volume carbon black (Raven™ 430) with about 10.5% by volume high density polyethylene (LB832, manufactured by Equistar) and about 52.5% copolymer (EBA705, manufactured by Equistar), as in Example 1, and then extruding into sheet and laminating in a continuous process. The laminated sheet was cut into individual laminates of 0.10 m x 0.41 m (4 inch x 16 inch).

The laminate was drilled with registration holes as in Example 1 and with holes having a diameter of 1.27 mm (0.050 inch) to create apertures in the laminate. Four layers of 0.038 mm (0.0015 inch)-thick layer of epoxy pre-preg (44N Multifilm, available from Arlon) and two layers of 1 oz Cu foil treated as in Example 2 were also drilled with registration holes suitable for alignment.

In the Claims

Please cancel claims 1 to 17.

In the Drawings

Please replace Figure 6 on page 3/9 of the drawings by Figure 6 on replacement sheet 3/9.

REMARKSAmendments

In the descriptive part of the specification, the status of this application as a continuation-in-part has been added, and various minor errors have been corrected.

In the claims, claims 1 to 17 have been cancelled.

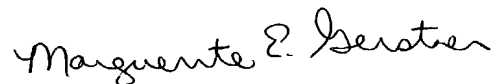
In the drawings, Figure 6 has been amended. As filed, Figure 6 incorrectly identified two elements on the lower right side of composite device 2 as element "12". It is apparent from reviewing the specification (page 20, lines 19 to 20) and the lower left corner of composite device 2 that the lower occurrence of "12" should be --9-- for insulating substrate 9. This proposed change is marked in red on the attached sheet 3/9.

Attached hereto is a marked-up version of changes made to the specification and claims by the current amendment. The attached page is captioned "Version with Markings to Show Changes Made".

Conclusion

It is believed that this application is now in condition for allowance and such action at an early date is earnestly requested. If, however, there are any outstanding issues which can be usefully discussed by telephone, the Examiner is asked to call the undersigned.

Respectfully submitted,



Marguerite E. Gerstner
Registration No. 32,695
Telephone (650) 361-2483

VERSION WITH MARKINGS TO SHOW CHANGES MADE

In the Specification

The following two paragraphs have been added before the heading beginning at page 1, line 3 of the specification (i.e. the heading "Background of the Invention"):

--Reference to Related Applications

This application is the national stage of International Application No. PCT/US00/25118, filed September 13, 2000, which is a continuation-in-part of U.S. Application No. 09/395,869, filed September 14, 1999. The disclosure of each of these applications is incorporated herein by reference.--

The paragraph beginning at page 20, line 19 of the specification has been amended as follows:

Figure 6 shows in cross-section a composite device 2 as in Figure 5 soldered to traces 41 and 43 on an [in] insulating substrate 9.

The paragraph beginning at page 22, line 8 of the specification has been amended as follows:

Figure 21 illustrates a composite device which has only one internal electrode 16, formed from a stack with only one internal conductive surface. A laminar element 17 is combined with the laminar element 76 [78]. The laminar elements can be pressed together to form a bond, so that no third laminar element is required to secure the laminar elements together. For example, 17 can comprise a PTC element and 76 [78] can comprise a dielectric substrate with adhesive properties.

The paragraph beginning at page 24, line 6 of the specification has been amended as follows:

One surface of one foil layer of each of two laminates was [were] patterned using an etching technique in which the surface was [they were] first coated with an etch resist, then imaged in a desired pattern. The etch resist was developed and etching was accomplished using cupric chloride before the resist was stripped away. These same foil layers were patterned to define the periphery of the individual devices and the residual conductive members. In addition, the outer edges of the metal foil on the laminate were etched to

provide an alternating cross directional pattern around the perimeter, as shown in Figure 2. Paths providing electrical continuity were utilized during the subsequent electrolytic plating of Sn/Pb.

The two paragraphs beginning at page 26, line 11 of the specification have been amended as follows:

A stacked assembly in accordance with Figure 26 was prepared by the following method. One laminate having a thickness of about 0.198 mm (0.0078 inch) was prepared by attaching a nickel/copper foil having a thickness of about 0.0356 mm (0.0014 inch) to both major sides of a 0.127 mm (0.005 inch)-thick sheet of conductive polymer. The conductive polymer was prepared by mixing about 37% by volume carbon black (Raven™ 430) with about 10.5% by volume high density polyethylene (LB832, manufactured by Equistar) and about 52.5% copolymer (EBA705, manufactured by Equistar), as in Example 1, [1.] and then extruding into sheet and laminating in a continuous process. The laminated sheet was cut into individual laminates of 0.10 m x 0.41 m (4 inch x 16 inch).

The laminate was drilled with registration holes as in Example 1 and with holes having a diameter of 1.27 [0.127] mm (0.050 inch) to create apertures in the laminate. Four layers of 0.038 mm (0.0015 inch)-thick layer of epoxy pre-preg (44N Multifilm, available from Arlon) and two layers of 1 oz Cu foil treated as in Example 2 [1] were also drilled with registration holes suitable for alignment.

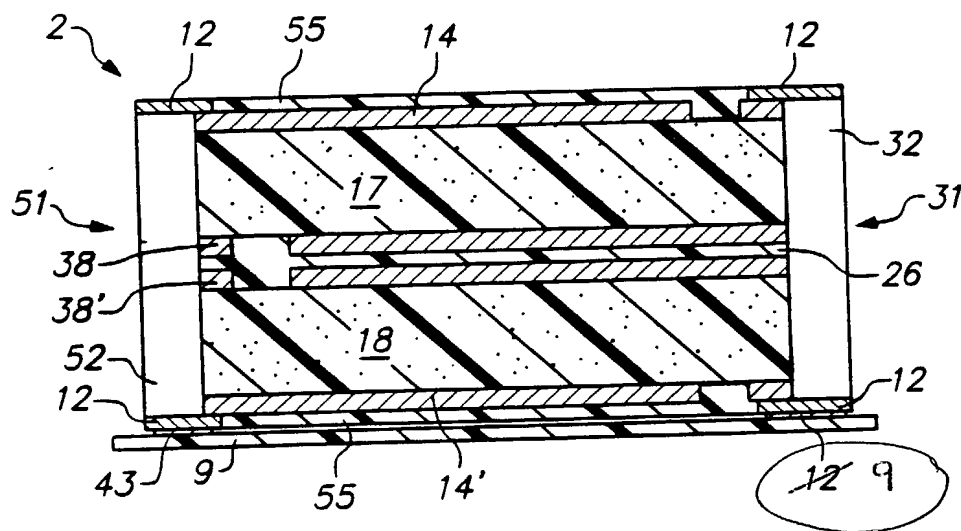
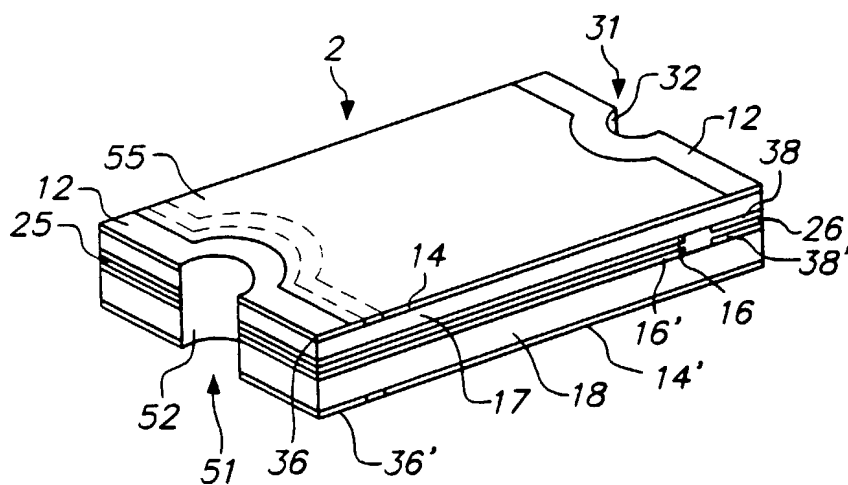
In the Claims

Claims 1 to 17 have been canceled.

In the Drawings

Figure 6 has been replaced by replacement Figure 6.

3/9



has a lower resistance for a given hold current, where "hold current" is the largest current which can be passed through a device without causing it to trip.

SUMMARY OF THE INVENTION

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As described in International Patent Publication No. WO99/53505 (Raychem Corporation, published October 21, 1999), the disclosure of which is incorporated herein by reference, composite devices can be prepared by sorting individual devices and then assembling the sorted devices into composite devices. Such a process can be tedious, as it may require that the resistance of each individual device be read. We have now found, in accordance with the present invention, that it is possible to prepare a multilayer assembly from which individual composite devices can be divided. Such an assembly allows preparation of a large number of composite devices simultaneously. Furthermore, because the process described herein allows the patterning of individual layers of the assembly before or after fabrication into the assembly, a variety of different devices can be prepared from the same starting layers. In addition, the composition of the layers can be easily varied, allowing the simple build-up of devices with combined functionality. Various interconnection schemes between layers can be simply implemented, and devices with multiple external electrical contacts can be made without changing the basic manufacturing process. All of these further add to the broad range of different devices which can be inexpensively mass-produced by the process disclosed herein.

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This invention provides methods and processes for which various operative steps can be carried out on an assembly which will yield a plurality of devices when subdivided into composite devices by subdividing along both x- and y-directions (where x and y correspond to directions in the plane of the laminar PTC elements). The ability to prepare devices in this way is a significant improvement over other methods, for example that described in International Patent Publication No. WO99/53505, because for this invention, individual devices do not need to be individually assembled, increasing the efficiency and therefore reducing the cost of the manufacturing process. Finally, the method of combining layers of materials to form composite devices disclosed herein allows an extremely simple yet adaptable method for forming a variety of devices without the necessity of changing the basic manufacturing process.

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In a first aspect this invention provides a process for manufacturing a composite polymeric circuit protection device, said process comprising

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- (1) providing a polymeric assembly comprising
- (a) providing first and second laminates, each of which comprises a laminar polymer element having at least one conductive surface,
- (b) providing a pattern of conductive material on at least one of the conductive surfaces on one laminate;
- (c) securing the laminates in a stack in a desired configuration, at least one conductive surface of at least one of the laminates comprising an external conductive surface of the stack, and
- (d) making a plurality of electrical connections between a conductive surface of the first laminate and a conductive surface of the second laminate; and
- (2) subdividing the stack into individual devices each of which comprises at least one electrical connection.

In a second aspect this invention provides a polymeric assembly comprising:

- (a) a first laminate comprising a laminar polymer element having at least one conductive surface having a pattern;
- (b) a second laminate comprising a laminar polymer element having at least one conductive surface having a pattern, said second laminate being secured to the first laminate in a stack so that the stack has first and second external conductive surfaces; and
- (c) a plurality of transverse conductive members which run through the first and second laminates between the first and second external conductive surfaces.

Using either the process or the assembly of the invention, devices can be made by creating electrode precursors in the form of conductive surfaces of appropriate shapes

upon resistive elements which are larger than the desired final shape, forming a stack of a plurality of resistive elements which is also larger than the desired final shape, and then subdividing the stack into individual devices. Electrodes of appropriate shapes can be made by removing unwanted portions of any one, or any combination, of the conductive surfaces. The removal can be accomplished by milling, stamping, or etching, for example. Alternatively, the electrode precursors can be formed by patterning conductive material onto any one or any combination of the PTC resistive element surfaces by chemical vapor deposition, electrodeposition, sputtering, etc. Conductive material may also be applied to the faces of the PTC resistive elements by use of an adhesive or tie layer. Electrical interconnection between a desired combination of the conductive surfaces of the plurality of resistive elements can be accomplished before the stack has been subdivided into individual devices. Alternatively, some or all of the electrical connections between desired electrodes or contact points can be made after the stack has been subdivided into composite devices. The electrical interconnection can be designed so that connection is made between some of the conductive surfaces of the stack or the electrodes of the device, but not all.

Thus in a third aspect, this invention provides a composite device, which can be made, for example, using the process of the first aspect of the invention or the assembly of the second aspect, comprising

- (1) first and second external laminar electrodes,
- (2) third and fourth internal laminar electrodes,
- (3) first and second laminar PTC resistive elements, each of which (i) exhibits PTC behavior, and (ii) comprises a laminar element composed of a PTC conductive polymer,

said first resistive element having a first face to which the first external electrode is secured and an opposite second face to which the third internal electrode is secured, and said second resistive element having a first face to which the second external electrode is secured and an opposite second face to which the fourth internal electrode is secured,

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- (d) is physically and electrically connected to the first external laminar electrode, the seventh internal laminar conductive member, the eighth internal laminar conductive member, and the second external laminar electrode, but is not connected to the third or the fourth internal electrode, and

- (11) a second transverse conductive member which

- (a) lies within the second aperture,

- (b) runs between the fifth external laminar conductive member and the sixth external laminar conductive member,

- (c) is secured to the first PTC element, the second PTC element and the third laminar polymer layer, and

- (d) is physically and electrically connected to the fifth external laminar conductive member, the third internal electrode, the fourth internal electrode, and the sixth external laminar conductive member, but is not connected to the first or second external electrode.

BRIEF DESCRIPTION OF THE DRAWINGS

The invention is illustrated in the accompanying drawings, in which Figure 1 is a perspective view of a section of a stack formed in the first aspect of the invention, which can be subdivided into a plurality of individual composite devices;

Figure 2 is an exploded view of a stack which has been patterned on the internal conductive surfaces;

Figure 3 is a plan view of the top of a section of a stack;

Figure 4 is a cross-sectional view of a section of a stack along line IV-IV in Figure

Figure 5 is a perspective view of a composite device of the invention;

Figure 6 is a cross-sectional view of a composite device mounted on a printed circuit board parallel to the board;

5 Figure 7 is a plan view of composite devices further illustrated in Figures 8, 9, 10,
11, 14, and 21;

Figures 8, 9, and 10 are cross-sectional views along line VIII-VIII in Figure 7 of composite devices with two elements connected in parallel;

Figure 11 is a cross-sectional view along line VIII-VIII in Figure 7 of a composite device with three elements connected in parallel;

Figure 12 is a plan view of another composite device with two elements connected
15 in parallel but with no residual conductive members as illustrated in Figure 13;

Figure 13 is a cross-sectional view along line XIII-XIII in Figure 12;

Figure 14 is a cross-sectional view along line VIII-VIII of Figure 7 of another
20 composite device with two elements connected in parallel;

Figure 15 is a cross-sectional view of a composite device with two elements connected in series:

25 Figure 16 is a plan view of a composite device with more than two external electrical connection points;

Figure 17 is an electrical diagram of the interconnection scheme of the individual devices connected together to form the composite devices of Figures 16 and 18 to 20.

Figures 18, 19, and 20 are cross-sectional views along lines XVIII-XVIII, XIX-XIX, and XX-XX, respectively, in Figure 16;

Figure 21 is a cross-sectional view of a composite device with two external
35 electrodes and one internal electrode;

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DETAILED DESCRIPTION OF THE INVENTION

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antioxidant, crosslinking agent, coupling agent, flame retardant, or elastomer. The PTC composition preferably has a resistivity at 23°C of less than 50 ohm-cm, particularly less than 10 ohm-cm, especially less than 5 ohm-cm. Suitable conductive polymers for use in this invention are disclosed for example in U.S. Patents Nos. 4,237,441 (van Konynenburg et al), 4,304,987 (van Konynenburg), 4,514,620 (Cheng et al), 4,534,889 (van Konynenburg et al), 4,545,926 (Fouts et al), 4,724,417 (Au et al), 4,774,024 (Deep et al), 4,935,156 (van Konynenburg et al), 5,049,850 (Evans et al), 5,378,407 (Chandler et al), 5,451,919 (Chu et al), 5,582,770 (Chu et al), 5,747,147 (Wartenberg et al), and 5,801,612 (Chandler et al), and U.S. Patent Application No. 09/364,504 (Isozaki et al), filed July 30, 1999). The disclosure of each of these patents and applications is incorporated herein by reference.

Alternatively, the PTC composition can be a ceramic material.

15 Laminar Elements

Devices of the invention preferably comprise PTC resistive elements which are laminar elements, and can be composed of one or more conductive polymer members, at least one of which is composed of a PTC material. When there is more than one conductive polymer member, the current preferably flows sequentially through the different compositions, as for example when each composition is in the form of a layer which extends across the whole device. When there is a single PTC composition, and the desired thickness of the PTC element is greater than that which can conveniently be prepared in a single step, a PTC element of the desired thickness can conveniently be prepared by joining together, e.g. laminating by means of heat and pressure, two or more layers, e.g. melt-extruded layers, of the PTC composition. When there is more than one PTC composition, the PTC element will usually be prepared by joining together, e.g. laminating by means of heat and pressure, elements of the different compositions.

Assemblies of the invention comprise first and second laminates, and may comprise additional laminates. The first and second laminates each comprise a laminar polymer element having at least one conductive surface, e.g. in the form of a metal foil electrode as described below. In this specification, each laminate is referred to as a layer. The laminar elements of the first and second laminates may comprise PTC compositions which are the same, or the layers may comprise different PTC compositions. For example, PTC compositions of different resistivities may be used, and an interconnection

scheme devised so that one layer can act as a heater, and a second layer can act as an overcurrent protection device. The layers may also comprise PTC compositions of different switching temperatures (i.e. the temperature at which the device switches from a low resistance to a high resistance state). For example, such a device may be useful for creating a two-tiered PTC temperature sensor, with one layer being the most sensitive for a lower temperature range, and the second layer being the most sensitive for a higher temperature range. Furthermore, one or more of the laminates may comprise a zero temperature coefficient of resistance (ZTC) composition or a negative temperature coefficient of resistance (NTC) composition.

It is not necessary that each of the laminates comprise a conductive layer. For example, other compositions which can be used for a laminar element in the composite devices comprise a dielectric material such as polyester or a filled dielectric material such as FR4 epoxy. This can function as an insulating layer which provides extra rigidity to the device, or the material can be chosen to assist in the mounting and packaging of the device. In addition, a laminar element can comprise a composition which has a relatively high thermal conductivity to aid in the thermal transfer between layers of the composite, or between a substrate and a layer of the composite for a surface mounted device. Conversely, a laminar element can comprise a composition which has a relatively low thermal conductivity to act as a thermal insulator between layers or between a layer and the substrate. When it is desired that the device have the capability to respond to an overvoltage, a layer of the composite can comprise a material which is normally insulating but becomes conducting when a certain voltage threshold level is reached. Such compositions include varistor particles dispersed in a polymeric matrix. Other compositions which may be useful for various embodiments of this invention include flame retardant materials, intumescants, and microwave absorbing materials to allow the heating of the device using radiation of a specific frequency range.

The thicknesses of the laminar elements comprising the assembly used to prepare a composite device may be different. For example, a very thin laminar element may be used as one layer to provide an extremely low resistance, and a thicker laminar element may be used as a second layer to provide mechanical strength.

Electrodes and Conductive Surfaces

Particularly useful devices made by the process of the invention comprise at least two metal foil electrodes, with polymer elements sandwiched between them. An especially useful device will comprise a stack comprising n polymeric PTC elements, each having two metal foil electrodes, and $(n-1)$ adhesive layers sandwiched between the PTC elements in an alternating pattern to form a composite device, with the PTC elements comprising the top and bottom components of the stack. This device will have the electrodes electrically connected such that the PTC elements will be connected in parallel, resulting in a composite device which has a low resistance at 20°C, generally less than 10 ohms, preferably less than 5 ohms, more preferably less than 1 ohm, particularly less than 0.5 ohm, with yet lower resistance being possible, e.g. less than 0.05 ohm. Particularly suitable foil electrodes are microrough metal foil electrodes, in particular as disclosed in U.S. Patents Nos. 4,689,475 (Matthiesen) and 4,800,253 (Kleiner et al), and in International Patent Publication No. WO95/34081 (Raychem Corporation, published December 14, 1995), the disclosure of each of which is incorporated herein by reference. The electrodes can be modified so as to produce desired thermal effects and so as to provide electrical contact points for various interconnection points between the layers of the composite device to give the desired functionality, and to provide electrical contact points for mounting the device onto printed circuit boards, sockets, clips, or other suitable applications. Examples of composite devices which incorporate multiple internal and external contact points are illustrated in Figures 16 to 20, 22, and 23.

Similar types of metal foil can be used to form the conductive surfaces of the laminates in the polymeric assembly. Alternatively, the conductive surface may be formed from a conductive ink, a sputtered or otherwise applied metal layer, a metal mesh, or another suitable layer. Particularly preferred conductive surfaces are those which can be etched, e.g. for patterning, and/or soldered easily. The conductive surface of the laminates has a resistivity at 25°C which is at least 100 times lower than the resistivity at 25°C of the polymer element to which it is attached.

The patterns may be the same on both sides of a given laminate, or they may be different. Additional patterns may be created at any point in the process, e.g. on an external conductive surface of the laminate once a stacked assembly is formed, or as attachments are made to internal conductive surfaces before the stacked assembly is completed.

Apertures and Cross-Conductors

The term “aperture” is used herein to denote an opening which, when viewed at right angles to the plane of the device,

(a) has a closed cross-section, e.g. a circle, an oval, or a generally polygonal shape, or

(b) has a reentrant cross-section, the term “reentrant cross-section” being used to denote an open cross-section which (i) has a depth at least 0.15 times, preferably at least 0.5 times, particularly at least 1.2 times, the maximum width of the cross-section, e.g. a quarter circle or a half circle or an open-ended slot, and/or (ii) has at least one part where the opposite edges of the cross-section are parallel to each other.

Since the invention involves assemblies which can be divided into a plurality of electrical devices, the apertures will normally be of closed cross-section, but if one or more of the lines of division passes through an aperture of closed cross-section, then the apertures in the resulting devices will have open cross-sections. Although for some embodiments, it is desirable that an open cross-section is a reentrant cross-section as defined above, in order to ensure that the cross-conductor, which passes through the aperture, is not damaged or dislodged during installation or use of the device, for other embodiments, it is preferred that the cross-conductor is a plating on one transverse flat face of the device. In order to produce such a device, it is preferred that the assembly, which is to be divided into a plurality of devices, has a plurality of elongate rectangular apertures, e.g. slots, each with metal plating thereon. The assembly is then divided so that each plated aperture provides a flat transverse conductive member on a number of devices.

The apertures in the assembly may be of different sizes and/or shapes to accommodate device configurations and current-carrying capabilities.

The aperture can be a circular hole, and this is satisfactory in many cases. However, if the assembly includes apertures which are traversed by at least one line of division, elongate apertures may be preferred because they require less accuracy in the lines of division.

When the aperture is not traversed by a line of division, it can be as small as is convenient for a cross-conductor having the necessary current-carrying capacity. Generally a single cross-conductor is all that is needed to make an electrical connection to the first electrode to the opposite side of the device. However, two or more cross-
5 conductors can be used to make the same connection. The number and size of the cross-conductors, and, therefore, their thermal capacity, can have an effect on the rate at which a circuit protection device will trip. Generally the apertures and cross-conductors can extend throughout all layers of the assembly. Alternatively, apertures and cross-
10 conductors can extend through only some layers of the assembly to form devices of different functionality.

The aperture can be formed before the cross-conductor is put into place, or the formation of the aperture and the placing of the cross-conductor can be carried out
15 simultaneously. A preferred procedure is to form an aperture, e.g. by drilling, slicing, routing or any other appropriate technique, and then to plate or otherwise coat or fill the interior surface of the aperture. The plating can be effected by electroless plating, or electrolytic plating, or by a combination of both. The plating can be a single layer or multiple layers, and can be composed of a single metal or a mixture of metals, in
20 particular a solder. The plating will often be formed on other exposed conductive surfaces of the assembly. If such plating is not desired, then the other exposed conductive surfaces can be masked or otherwise desensitized, or undesired plating can be selectively removed. The invention includes the possibility that the plating will produce not only the cross-conductor but also at least part of the laminar conductive members in the device.

25 The plating techniques which are used for making conductive vias through insulating circuit boards can be used in the present invention.

Another technique for providing the cross-conductors is to place a moldable or
30 liquid conductive composition in preformed apertures, and if desired or necessary, to treat the composition, while it is in the apertures, so as to produce cross-conductors of desired properties. The composition can be supplied selectively to the apertures, e.g. by means of a screen, or to the whole assembly, if desired after pretreating at least some of the assembly so that the composition does not stick to it. For example, a molten conductive
35 composition, e.g. solder, could be used in this way, if desired, using wave soldering techniques.

The cross-conductor can also be provided by a preformed member, e.g. a metal rod or tube such as a rivet. When such a preformed member is used, it can create the aperture as it is put in place in the device.

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The cross-conductor can partially or completely fill the aperture. When the aperture is partially filled, it can be further filled (including completely filled) during the process in which the device is connected to other electrical components, particularly by a soldering process. This can be encouraged by providing additional solder in and around the aperture, especially by including a plating of solder in and around the aperture. Normally at least a part of the cross-conductor will be put in place before the device is connected to other electrical components. However, the invention includes the possibility that the cross-conductor is formed during such a connection process, as for example by the capillary action of solder during a soldering process.

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A cross-conductor may be designed such that it electrically connects some of the layers, i.e. some of the laminates, together, but not all. Such cross-conductors are depicted in Figure 15. A method for making such a cross-conductor would comprise forming an aperture which is larger than the desired size for the cross-conductor, filling the aperture with an insulating substance, forming an inner aperture within the insulating substance, and plating the inner aperture to render it conductive. This method insulates the internal electrodes from the cross-conductor, yet allows the external electrodes to be electrically connected.

25 Connectors which are not Cross-Conductors

The electrical connection(s) between the electrode(s) and any residual member(s) on the various faces of the PTC resistive elements is preferably through a cross-conductor as described above. However, it can be of any kind, for example a connector which will remain in place even if it is not bonded to the other parts of the device, for example a U-shaped member which extends around the ends of a layer or combination of layers of the device.

Residual Laminar Conductive Members

A preferred embodiment of a device of the invention comprises an additional (residual) conductive member which is secured to the same face of the PTC element as the second electrode, but is separated therefrom. This residual laminar conductive member which, with the cross conductor or other connector, can be present to provide an electrical path to other electrodes, is formed by removing part of a laminar conductive member, the remainder of the of the laminar conductive member then being an electrode. Residual laminar conductive members may be present on both internal and external faces of the laminar elements. The shape of the residual laminar conductive member, and the shape of the gap between the residual member and an electrode, can be varied to suit the desired characteristics of the device and for ease of manufacture. The residual conductive member is conveniently a small rectangle at one end of a rectangular device, separated from an electrode by a rectangular gap. Alternatively, the residual member can be an island separated from the electrode by a gap of closed cross-section. Devices can also be designed without a residual laminar conductive member, as shown in Figures 12 and 13.

Additional Laminar Elements

The first and second laminar PTC resistive elements of the device or the first and second laminates of the assembly can be physically secured together in a stack, using a third laminar element between them. The third laminar element may comprise an electrically nonconductive adhesive, e.g. a hot-melt adhesive or a curable bonding material, to which fillers can be added to achieve particular thermal or mechanical properties. The third laminar element can also comprise curable monomeric organic or inorganic systems, such as epoxies, acrylates, allyls, urethanes, phenolics, esters, alkyds, etc. If it is desired that the laminar element act as an electrical insulator, then it is preferred that the resistivity is at least 10^6 ohm-cm, particularly at least 10^9 ohm-cm. For some embodiments it may be desired that the third laminar element comprise a conductive material. For these embodiments, the third laminar element serves to connect the layers together electrically as well as physically. A composite device configuration incorporating a conductive third laminar element is illustrated in Figure 15. For other embodiments, it may be desired that the third element comprise a conductive material which is electrically conductive in only one direction (see Figure 14). The third laminar element can also provide other functions, e.g. a thermally conductive layer to facilitate thermal transfer between the layers of the composite device.

Alternatively, devices can be designed which do not include a separate laminar layer to secure the elements of the device together. For example, a device can be made which is similar to that depicted in Figure 8, with the laminar element 26 eliminated. The cross-conductors 32 and 52 can be relied upon to both electrically connect the layers together in parallel, and to physically secure the layers together. Figure 21 depicts another example where the composite device does not require a separate laminar element between the layers.

10 Devices

In a simple device, as shown in Figure 5 there are two external electrodes, two internal electrodes, two cross-conductors or other connectors, and four residual conductive members. This configuration is useful since the device will then be symmetrical top to bottom, allowing for ease of installation by automated equipment or otherwise.

Particularly preferred circuit protection devices of the invention have a resistance at 23°C of less than 1 ohm, preferably less than 0.5 ohm, particularly less than 0.3 ohm, especially less than 0.1 ohm, and comprise first and second laminar PTC resistive elements, each of which (a) is composed of a conductive polymer which has a resistivity at 23°C of less than 50 ohm-cm, preferably less than 10 ohm-cm, particularly less than 5 ohm-cm, and which exhibits PTC behavior, and (b) has a first face and a second face. A first external metal foil electrode contacts the first face of the first PTC element and a second external metal foil electrode contacts the first face of the second PTC element. Third and fourth internal metal foil electrodes contact the second faces of the first and second PTC elements, respectively. The device preferably has a fifth and sixth residual external metal foil conductive members, the fifth contacting the first face of the first PTC element and spaced apart from the first external electrode, and the sixth contacting the first face of the second PTC element and spaced apart from the second external electrode. Generally there are seventh and eighth residual internal metal foil conductive members, the seventh contacting the second face of the first PTC element and spaced apart from the third internal electrode, and the eighth contacting the second face of the second PTC element and spaced apart from the fourth internal electrode. The device may also comprise one or more additional laminar polymer elements, which may be conductive or insulating. Preferably one of the additional elements is a third laminar polymer element

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Processes

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member, can also be of any suitable shape. The process steps prior to the division can in general be carried out in any convenient sequence. For example, it is often convenient to pattern the internal conductive surfaces prior to assembling the stack, and to pattern the external conductive surfaces after assembly. However, it is possible to pattern both internal and external conductive surfaces prior to assembly. The patterning of a conductive surface can be the same as or different from that on other conductive surfaces in the stack, depending on the desired functionality of the final device. For example, Figures 5, 6, 8, 9, 11 and 12 show devices which have internal electrodes which are the mirror images of external electrodes. Figures 10 and 18 to 20 show devices which have internal electrodes which are patterned differently than external electrodes. Often, it is useful to pattern conductive surfaces by removing, e.g. by etching, stamping, or milling, conductive material. Alternatively, the pattern can be produced by an additive process, e.g. screen printing, sputtering, or deposition. For some applications, it is useful to remove strips of conductive material in staggered strips alternately from opposite sides of a laminate layer to balance the physical stresses in the product. The resulting pattern will contain gaps or recesses suitable for separating a second electrode from a residual member in a device, separating one device from another, providing delineation for subdividing the assembly into individual devices, allowing for orientation of individual laminates or the assembled stack, or providing marking.

Cross-conductors, i.e. electrical connections, can be formed before or after the laminates are formed into the stack. If it is desired to form cross-conductors which do not traverse all layers of the stack, it may be convenient to form them for the desired laminate layers only, and then assemble the stack. Alternatively, using a blind via process, the connection can be made after the stack is assembled. Assembly of the stack can be accomplished in stages, for example, some laminates are prepared and secured together, some further processing steps are performed on the partially constructed stack (e.g. formation and plating of cross-conductors), and then other laminates can be secured to this partially constructed stack to complete the assembly. Subdivision of the stack into composite devices can be accomplished using a variety of techniques such as sawing, shearing, dicing, punching, and snapping, e.g. by using a saw, a shear, a blade, a wire, a waterjet, a snapping device, a laser, or a combination of these. Some preferred processes for making devices from a single laminate are disclosed in U.S. Patent No. 5,864,281. These processes may be adapted for the subdivision of a stack of laminates such as that described herein. Alternatively, some of the steps in the process, e.g. securing the

laminates in a stack and making a plurality of electrical connections by means of cross-conductors, can be accomplished simultaneously.

5 In order to minimize curling or warping due to shrinkage during subsequent processing steps, it may be preferred to apply a pattern around the perimeter of at least one laminate. The preferred pattern is produced by a process comprising selectively removing conductive material from at least one conductive surface of each laminate in an alternating cross-directional design, e.g. in the shape of a "W" or a "Z", around the perimeter of the laminate such that there is electrical continuity between the outer edge of
10 the conductive surface for the external layers.

Part or all of the external conductive surface may be covered with an insulating layer, e.g. a solder mask or marking material such as that disclosed in U.S. Patent No. 5,831,510.

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The invention is illustrated in the accompanying drawings, in which features such as apertures and the thicknesses of components are not drawn to scale to make them more clear. Figure 1 is a perspective view of a section of a stack 1 which has two laminar elements 7 and 8, each of which has patterned external conductive surfaces 3 and 3', respectively, and patterned internal conductive surfaces 5 and 5', respectively. The
20 elements 7 and 8 are secured to each other with insulating laminar element 6. Tubular cross conductors 11 extend through the stack as shown.

Figure 2 is an exploded view of a stack under construction according to the process of the invention. Two laminar elements 7 and 8, each having patterned internal conductive surfaces 5 and 5', respectively, and unpatterned external conductive surfaces 3 and 3', respectively, are included in the stack, with a laminar element 6 sandwiched between 7 and 8. Registration holes 4 are used to orient the elements of the stack uniquely, align them relative to each other, and to position the stack for subsequent
25 processes such as patterning of external surfaces and the formation of apertures.

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Figure 3 is a plan view of a patterned external conductive surface 3 of a section of a stack. C marks where the subdivision of the stack into composite devices will occur. Figure 4 is a cross-sectional view along line IV-IV of Figure 3. The stack includes laminar elements 7 and 8 each having internal conductive surfaces 5 and 5' and external
35 conductive surfaces 3 and 3', and laminar element 6 which is sandwiched between 7 and

8. The stack has been plated to provide the tubular cross conductors 11 in each of the apertures (and a plating 12 on other exposed external surfaces of the stack). The stack as shown will be subdivided through the tubular cross conductors, forming cross conductors with semicircular cross-sections.

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Figure 5 is a perspective of a composite device 2 formed by subdividing a stack. Two laminar PTC elements 17 and 18, each having external electrodes 14 and 14', respectively, external residual conductive members 36 and 36', internal electrodes 16 and 16' and internal residual conductive members 38 and 38', are secured together with
10 laminar element 26. A first transverse member 31 and a second transverse member 51 are hollow tubes formed by a plating process in which the exposed surfaces are plated with copper and then with solder to form a first plating 32 on transverse member 31, and a second plating 52 on transverse member 51. A dielectric coating 55 covers the external surfaces of the device except where it is desired to make electrical connection. A plating
15 12 is applied to the exposed portions of the external electrodes. The region between the dashed lines indicates portions under the dielectric coating 55 in which there is no electrode material.

Figure 6 shows in cross-section a composite device 2 as in Figure 5 soldered to
20 traces 41 and 43 on an insulating substrate 9.

Figure 7 is a plan view for a variety of composite devices shown in cross-section along line VIII-VIII in Figures 8 to 11, 14, and 21. The dashed lines indicate portions positioned underneath the dielectric layer 55, wherein the electrode material is not
25 present. Note that for the cross-sectional views in Figures 8-11, 14 and 21, the dielectric layer 55 is not shown. Figures 8 and 9 show two configurations for PTC elements connected in parallel. For the device shown in Figure 8 when it is in its switched, high resistance state, the laminar element 26 will have no potential drop across it when a potential is applied to one external electrode 14 and one external residual conductive
30 member 36. However, for the device shown in Figure 9, when in its switched state, the laminar element 26 will have a potential drop across it for the same external electrical connection. Figure 10 shows a variant of the device shown in Figure 8, with no internal residual conductive members. Figure 11 shows a composite device formed by connecting three laminar elements 17, 18, and 19 in parallel, with laminar element 26 between 17 and
35 18, and laminar element 26' between 18 and 19. The version of the device shown has

internal electrodes 16, 16', 16'' and 16''', and internal residual conductive members 38, 38', 38'', and 38'''.

Figure 12 is a plan view of a device with no residual conductive members; a cross-sectional view along XIII-XIII is shown in Figure 13. Dashed lines indicate regions positioned under the external dielectric layer 55 where electrode material is not present. Dielectric layer 55 is not shown in Figure 13.

Figure 14 is a composite device formed by the process of this invention, in which cross conductors do not extend completely through all layers of the stack. To make the device as shown here, cross conductors 59 extend only between external and internal conductive surfaces of each laminar element of the stack; the laminar elements are then secured together using an anisotropically conductive substance 57 which conducts only in the z-direction, where z- refers to the direction from bottom to top of the composite device. Conductive substance 57 provides electrical connection between internal residual conductive members 38 and 38' and between internal electrodes 16 and 16', without causing 38 or 38' to be shorted to 16 or 16'.

Figure 15 shows a composite device in which laminar elements 17 and 18 are connected in series. The laminar elements are secured together in the stack using a conductive material 61. Cross-conductors are made in the stack which connect to some conductive surfaces, but not all. To form such a cross conductor, apertures larger than the desired dimensions of the cross conductor are formed through the stack. The apertures are then filled with an insulating substance 63, and two smaller apertures 65 and 67 are formed within the volumes filled with the insulator 63. The apertures 65 and 67 and exposed external electrodes have platings 32 and 52.

Figure 16 shows a plan view of a composite device which includes two devices and has three external electrical connection points. A diagram of the electrical connections for the two devices 77 and 79 is shown in Figure 17.

Figure 18 shows a cross-section along line XVIII-XVIII in Figure 16. Cross-conductor 52 is in electrical contact with the internal residual members 38 and 38'. A gap separates the residual members 38 and 38' from internal electrodes 16 and 16'. Additional conductive member 46' is also present.

Figure 19 shows a cross-section along line XIX-XIX in Figure 16. Cross-conductor 72 is in electrical contact with internal residual conductive members 38 and 38'. A gap separates the residual members 38 and 38' from internal electrodes 16 and 16'. Additional conductive member 46 is also present.

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Figure 20 shows the cross-sectional view along XX-XX in Figure 16.

Figure 21 illustrates a composite device which has only one internal electrode 16, formed from a stack with only one internal conductive surface. A laminar element 17 is combined with the laminar element 78. The laminar elements can be pressed together to form a bond, so that no third laminar element is required to secure the laminar elements together. For example, 17 can comprise a PTC element and 78 can comprise a dielectric substrate with adhesive properties.

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Figure 22 is a plan view of a composite device which has multiple cross conductors to provide extra current carrying capacity, and extra robustness should one or both of the other cross conductors become damaged or form an open circuit. The dashed line indicates regions where there is no electrode material; the dotted circle indicates the region of an additional cross-conductor.

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Figure 23 is a cross-sectional view along XXIII-XXIII in Figure 22 (dielectric layer 55 not shown). A third aperture 81 has a metal plating 82 and forms an additional electrical connection between the internal electrodes 16 and 16'. Note that there is a region around the external electrodes 14 and 14' where no electrode material is present.

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Figure 24 is an exploded view of a stack 1 in which three etched conductive laminate layers 107,108,109 are attached to one another by means of nonconductive laminar layers 106',106'' in the form of adhesive layers. Additional nonconductive layers 106 and 106''' connect metal foil layers 110,111 to etched laminate layers 107 and 109, respectively. The resulting stack can be divided into individual devices 2, as shown in Figure 25. Following etching and/or other processing steps, segments of metal foil layers 110,111 remain on exposed adhesive surfaces 116,116', respectively, as pads for connection to a circuit board or other substrate. Present on each device are first transverse member 31 with first plating 32 and second transverse member 51 with second plating 52.

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Figure 26 is an exploded view of a stack 1 in which a single etched and drilled conductive laminate layer 117 is sandwiched between two nonconductive laminar layers 116, 116'. Each nonconductive laminar layer, which may be an adhesive, e.g. an epoxy pre-preg, may comprise one or more separate layers. Laminar metal foil layers 120, 121 are attached to nonconductive laminar layers 116, 116', and form the outer layers of the stack. When the layers are laminated together by means of heat and pressure, the adhesive will fill the apertures in conductive laminate 117. Following processing, individual devices 2, shown in Figure 27, can be separated from stack 1. Electrical connection pads 122, formed from metal foil layer 120, are used to attach one or more electrical components, e.g. a silicon device, to the surface of the device. Attachment of components is disclosed in International Patent Application No. PCT/US00/07081 (filed March 17, 2000), the disclosure of which is incorporated herein by reference. Electrical connection pads 123, formed from metal foil layer 121, are used to attach the device to a circuit board or other substrate. First and second transverse members 31 and 51, respectively, are plated with layers 32 and 52. An "isolated" transverse member or via 124 is also present. This is formed from an adhesive-filled aperture through which another hole is drilled and plated.

The invention is illustrated by the following Examples.

Example 1

A stack in accordance with Figures 1 and 2 was prepared by the following method. Two laminates, each having a thickness of about 0.264 mm (0.0104 inch) were prepared by attaching a nickel/copper foil having a thickness of about 0.0356 mm (0.0014 inch) to both sides of a 0.193 mm (0.0076 inch)-thick sheet of conductive polymer. The conductive polymer was prepared by mixing about 40% by volume carbon black (Raven™ 430, available from Columbian Chemicals) with about 60% by volume high density polyethylene (Chevron™ 9659, available from Chevron), and then extruding into sheet and laminating in a continuous process. The laminated sheet was cut into individual laminates of 0.30 m x 0.41 m (12 inch x 16 inch). The laminates were irradiated to 4.5 Mrad using a 4.5 MeV electron beam.

Each of the laminates was drilled in an asymmetric pattern around its the periphery to provide holes and slots to register the laminates in a known x-y orientation in the plane of the laminate. These registration holes and slots were used to align plaques

relative to each other in forming a stack, and for subsequent alignment of the tooling for imaging, solder masking, and plating operations. A 0.0762 mm (0.003 inch)-thick layer of modified acrylic adhesive (Pyrallux™ LFO, available from DuPont) was also drilled with registration holes suitable for alignment.

One surface of one foil layer of each of two laminates were patterned using an etching technique in which they were first coated with an etch resist, then imaged in a desired pattern. The etch resist was developed and etching was accomplished using cupric chloride before the resist was stripped away. These same foil layers were patterned to define the periphery of the individual devices and the residual conductive members. In addition, the outer edges of the metal foil on the laminate were etched to provide an alternating cross directional pattern around the perimeter, as shown in Figure 2. Paths providing electrical continuity were utilized during the subsequent electrolytic plating of Sn/Pb.

A stack was formed by positioning two laminates with their pattern-matched etched sides facing inward, and with an adhesive layer sandwiched in between, as shown in Figure 2. A fixture was used to align the layered laminates, and the stack was heated while under pressure to permanently attach the layers into a laminated structure. The thickness of the stack formed was approximately 0.61 mm (0.024 inch).

Holes having a diameter of 0.94 mm (0.037 inch) were drilled through the entire stack to form apertures. The stack was treated with a plasma etch. The apertures were then coated with colloidal graphite, and the stack was electrolytically plated with copper.

The external metal foil layers of the stack were then patterned by etching. The registration holes were used to ensure the pattern which was etched was properly aligned with the internal layers which were etched previously. An alternating cross-directional pattern around the edges was etched as previously described.

A soldermask (Finedel DSR 2200 C-7, available from Tamura Kaken Co., Ltd.) was applied to one external metal foil layer of the stack, tack-cured, and then applied to the second external metal foil layer of the stack, and tack-cured. The soldermask was then imaged and developed. Marks were applied to identify individual parts, and the panel was then heated to fully cure the mask. A SnPb solder plate was deposited in the solder pad regions for use in attaching devices to circuit boards.

The assembly was divided to produce devices as shown in Figure 5 by first separating the assembly into strips using a shear or saw, and then subdividing the strips into individual devices by mechanical snapping using a two-step process in which the strips were first bent to form a fracture in the conductive polymer at the isolation line, and then were sheared along that isolation line. The devices produced had dimensions of about 4.5 mm x 3.4 mm x 0.7 mm (0.179 inch x 0.133 inch x 0.029 inch), and a resistance of about 0.031 ohm. Following installation onto a printed circuit board by solder reflow, the devices had a resistance of about 0.050 ohm.

Example 2

A stack in accordance with Figure 24 was prepared by the following method. Three laminates were prepared, irradiated, and drilled with registration holes as in Example 1. Four layers of modified acrylic adhesive as in Example 1, and two layers of 1 oz. Cu foil (0.034 mm (0.00135 inch) thick) which was grey-oxide treated on one side were also drilled with registration holes suitable for alignment. Using the etching technique of Example 1, the outer surfaces of both foil electrodes on all three laminates were patterned to define the periphery of the individual devices and the residual conductive members, and to define the alternating cross directional pattern on the periphery of the panel.

A stack was formed by positioning one layer of the Cu foil on the bottom (treated side up), followed by one adhesive layer, the three laminates with their pattern-matched etched sides oriented in the fixture and with an adhesive layer sandwiched in between each layer, followed by one adhesive layer on the topmost laminate, and then one Cu foil layer placed on the top (treated side down). A fixture was used to align the layered laminates, and the stack was heated while under pressure to permanently attach the layers into a laminated structure. The thickness of the resulting stack was approximately 1.19 mm (0.047 inch). Holes having a diameter of 0.94 mm (0.037 inch) were drilled through the entire stack to form apertures. The stack was treated with a plasma etch, the apertures were coated with colloidal graphite, and the stack was electrolytically plated with copper.

The external metal foil layers of the stack were then patterned by etching using the registration holes to ensure proper alignment. An alternating cross directional pattern around the edges was etched as previously described.

Marks and solder were applied as in Example 1. The stacked assembly was then divided to produce devices as shown in Figure 25 using the procedure of Example 1. The devices produced had dimensions of about 4.5 mm x 3.4 mm x 1.2 mm (0.179 inch x 0.133 inch x 0.047 inch), and a resistance of about 0.018 ohm. Following installation onto a printed circuit board by solder reflow, the devices had a resistance of about 0.029 ohm.

Example 3

A stacked assembly in accordance with Figure 26 was prepared by the following method. One laminate having a thickness of about 0.198 mm (0.0078 inch) was prepared by attaching a nickel/copper foil having a thickness of about 0.0356 mm (0.0014 inch) to both major sides of a 0.127 mm (0.005 inch)-thick sheet of conductive polymer. The conductive polymer was prepared by mixing about 37% by volume carbon black (Raven™ 430) with about 10.5% by volume high density polyethylene (LB832, manufactured by Equistar) and about 52.5% copolymer (EBA705, manufactured by Equistar), as in Example 1. and then extruding into sheet and laminating in a continuous process. The laminated sheet was cut into individual laminates of 0.10 m x 0.41 m (4 inch x 16 inch).

The laminate was drilled with registration holes as in Example 1 and with holes having a diameter of 0.127 mm (0.050 inch) to create apertures in the laminate. Four layers of 0.038 mm (0.0015 inch)-thick layer of epoxy pre-preg (44N Multifilm, available from Arlon) and two layers of 1 oz Cu foil treated as in Example 1 were also drilled with registration holes suitable for alignment.

The outer surfaces of both foil electrodes on the laminate were patterned using an etching technique as described in Example 1, to define the residual conductive members, as well as additional etched features which acted as registration fiducial marks for subsequent isolation processes.

A stack was formed by positioning one layer of the Cu foil on the bottom (treated side up), followed by two pre-preg layers (shown as a single layer in Figure 26), the laminate layer, two pre-preg layers, and then one Cu foil layer placed on the top (treated

side down). A fixture was used to align the layers, and the stack was heated while under pressure to permanently attach the layers into a laminated structure and to force the epoxy to completely fill the apertures in the laminate. The thickness of the stack formed was approximately 0.61 mm (0.024 inch).

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Holes having a diameter of 0.94 mm (0.037 inch) and 0.57 mm (0.023 inch) were drilled through the entire stack to form apertures, and holes having a diameter of 0.57 mm (0.023 inch) were drilled through the entire stack to form apertures which were centered on the epoxy filled aperture; this latter aperture was isolated from the laminate's electrode by the epoxy. The stack was treated with a plasma etch, the apertures were coated with colloidal graphite, and the stack was electrolytically plated with copper.

The external metal foil layers of the stack were then patterned by etching. The registration holes were used to make sure the pattern which was etched was properly aligned with the internal layers which were etched previously.

To produce devices as shown in Figure 27, the assembly was divided by a saw, slicing the length of a panel in one direction and then rotating the panel 90 degrees and dicing the width of the panel in one direction, using the etched fiducial features on the laminate as saw locating marks. The devices produced had dimensions of about 4.5 mm x 13.77 mm x 0.61 mm (0.177 inch x 0.542 inch x 0.024 inch)

These individual devices were heat-treated on a belt furnace to heat the devices to above the polymer melting temperature ($>130^{\circ}\text{C}$), cooled to room temperature, and then irradiated to 7 Mrad using a cobalt radiation source.

The resulting devices had a resistance of about 0.028 ohm when measuring across the conductive polymer laminate and $>1 \times 10^6$ ohm when measuring across the isolated via and the conductive polymer laminate. Following installation onto a printed circuit board or onto Ni leads by solder reflow, the devices had a resistance of about 0.042 ohm when measuring across the conductive polymer laminate and $>1 \times 10^6$ ohm when measuring across the isolated via and the conductive polymer laminate. The devices were suitable for attachment of electrical components directly onto the device, and the apertures and transverse conductive members were positioned so that, depending on the exact electrical connection, the attached electrical component, e.g. a circuit board element,

What is claimed is:

1. A process for manufacturing a composite polymeric circuit protection device, said process comprising
 - (1) providing a polymeric assembly comprising
 - (a) providing first and second laminates, each of which comprises a laminar polymer element having at least one conductive surface,
 - (b) providing a pattern of conductive material on at least one of the conductive surfaces on one laminate;
 - (c) securing the laminates in a stack in a desired configuration, at least one conductive surface of at least one of the laminates comprising an external conductive surface of the stack, and
 - (d) making a plurality of electrical connections between a conductive surface of the first laminate and a conductive surface of the second laminate; and
 - (2) subdividing the stack into individual devices each of which comprises at least one electrical connection.
2. A process according to claim 1, wherein the pattern in step (b) is formed by selectively removing a portion of conductive material from at least one of the conductive surfaces on one laminate, preferably by etching, milling, or stamping.
3. A process according to claim 1, which further comprises providing a pattern of conductive material on at least one of the external conductive surfaces, preferably by selectively removing a portion of conductive material from the external conductive surface.
4. A process according to claim 3, wherein at least one of the patterned external conductive surfaces is at least partially covered with an insulating layer

5. A process according to claim 3, wherein the patterns on the internal and external conductive surfaces are different.
6. A process according to claim 1, wherein an additional conductive layer is added to at least part of at least one of the external conductive surfaces.
7. A process according to claim 1 wherein steps (c) and (d) are performed simultaneously.
8. A process according to claim 1, wherein at least one laminate is marked to provide a unique identification of orientation, preferably wherein the laminate markings provide delineation for subdividing into individual devices.
9. A process according to claim 1, wherein the assembly comprises a third laminate.
10. A process according to claim 1, wherein the laminates are secured to each other in the stack by an adhesive.
11. A process according to claim 1, wherein electrical connection is made between conductive surfaces of the first and second laminates in the stack by (i) forming an aperture which extends through the stack, and (ii) forming a conductive member within the aperture.
12. A process according to claim 1, wherein the electrical connections are positioned so that the individual device comprises at least two electrical connections.
13. A process according to claim 1, wherein the laminar polymer element in at least one of the laminates comprises a PTC conductive polymer composition.
14. A process according to claim 13, wherein (a) the laminar polymer element in each laminate comprises a PTC conductive polymer composition and (b) the PTC conductive polymer composition in each laminate is the same as or different from the PTC conductive polymer composition in the other laminates.

15. A process according to claim 1, wherein at least one of the laminar polymeric elements comprises a ZTC conductive polymeric material, an NTC conductive polymeric material, or an insulating polymeric material.
16. A process according to claim 1, wherein the individual devices are subdivided from the assembly using a saw, a shear, a blade, a wire, a waterjet, a snapping device, a laser, or a combination of these.
17. A process according to claim 1 wherein the conductive surface on each laminate comprises a metal foil.
18. A polymeric assembly comprising:
 - (a) a first laminate comprising a laminar polymer element having at least one conductive surface having a pattern;
 - (b) a second laminate comprising a laminar polymer element having at least one conductive surface having a pattern, said second laminate being secured to the first laminate in a stack so that the stack has first and second external conductive surfaces; and
 - (c) a plurality of transverse conductive members which run through the first and second laminates between the first and second external conductive surfaces.
19. A composite device comprising
 - (1) first and second external laminar electrodes,
 - (2) third and fourth internal laminar electrodes,
 - (3) first and second laminar PTC resistive elements, each of which (i) exhibits PTC behavior, and (ii) comprises a laminar element composed of a PTC conductive polymer,

said first resistive element having a first face to which the first external electrode is secured and an opposite second face to which the third internal electrode is secured, and said second resistive element having a first face to which the second external electrode is secured and an opposite second face to which the fourth internal electrode is secured,

- (4) a fifth external laminar conductive member which is (i) secured to the first face of the first PTC resistive element, and (ii) is spaced apart from the first external electrode,
- (5) a sixth external laminar conductive member which (i) is secured to the first face of the second PTC resistive element, and (ii) is spaced apart from the second external electrode,
- (6) a seventh internal laminar conductive member which (i) is secured to the second face of the first PTC resistive element, and (ii) is spaced apart from the third internal electrode,
- (7) an eighth internal laminar conductive member which (i) is secured to the first face of the second PTC resistive element, and (ii) is spaced apart from the fourth internal electrode,
- (8) a first aperture which runs between the first external electrode of the first laminar PTC element and the second external electrode of the second laminar PTC element,
- (9) a second aperture which runs between the fifth external laminar conductive member of the first laminar PTC element and the sixth external laminar conductive member of the second laminar PTC element,
- (10) a first transverse conductive member which
 - (a) lies within the first aperture,

- (b) runs between the first external electrode of the first laminar PTC element and the second external electrode of the second laminar PTC element,
 - (c) is secured to the first PTC element, the second PTC element and the third laminar element, and
 - (d) is physically and electrically connected to the first external laminar electrode, the seventh internal laminar conductive member, the eighth internal laminar conductive member, and the second external laminar electrode, but is not connected to the third or the fourth internal electrode, and
- (11) a second transverse conductive member which
- (a) lies within the second aperture,
 - (b) runs between the fifth external laminar conductive member and the sixth external laminar conductive member,
 - (c) is secured to the first PTC element, the second PTC element and the third laminar polymer layer, and
 - (d) is physically and electrically connected to the fifth external laminar conductive member, the third internal electrode, the fourth internal electrode, and the sixth external laminar conductive member, but is not connected to the first or second external electrode.

20. A device according to claim 19 which further comprises a third laminar element which (i) comprises an insulating polymer, (ii) is inserted between the first and second laminar PTC resistive elements, and (iii) secures the first laminar PTC element to the second PTC element.

ABSTRACT

5 A process for manufacturing a composite polymeric circuit protection device in
which a polymeric assembly is provided and is then subdivided into individual devices
(2). The assembly is made by providing first and second laminates (7,8), each of which
includes a laminar polymer element having at least one conductive surface, providing a
pattern on at least one of the conductive surfaces on one laminate, securing the laminates
in a stack (1) in a desired configuration, at least one conductive surface of at least one of
10 the laminates forming an external conductive surface (3) of the stack, and making a
plurality of electrical connections (31,51) between a conductive surface of the first
laminate and a conductive surface of the second laminate. The laminar polymer elements
may be PTC conductive polymer compositions, so that the individual devices made by the
process exhibit PTC behavior.

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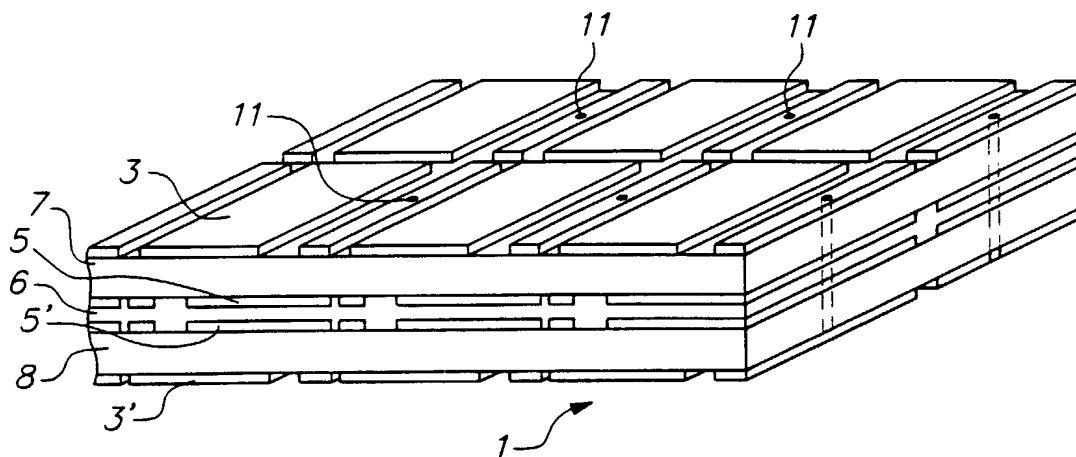


FIG. 1

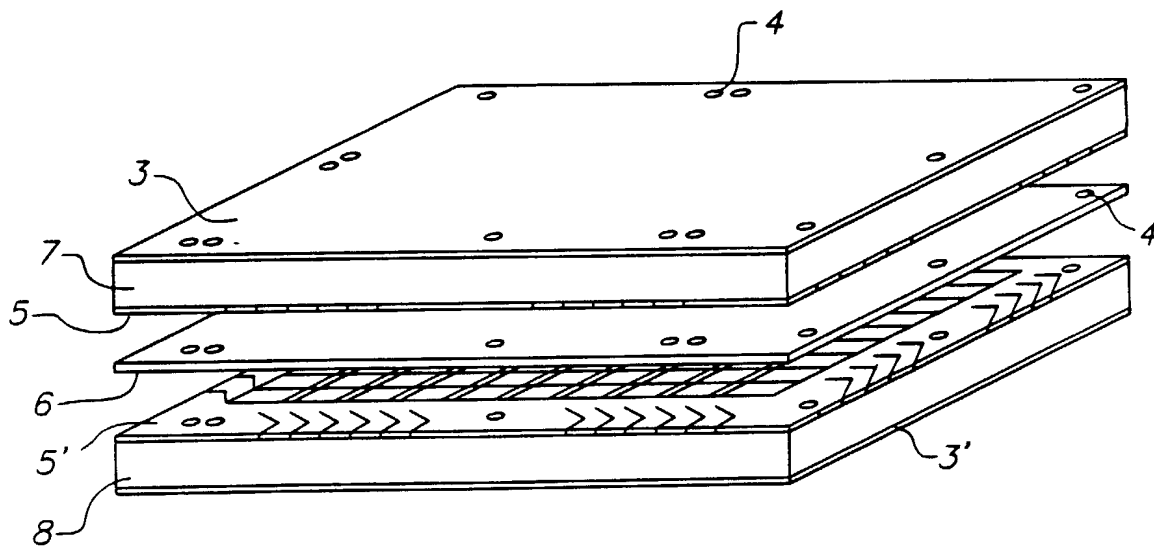


FIG. 2

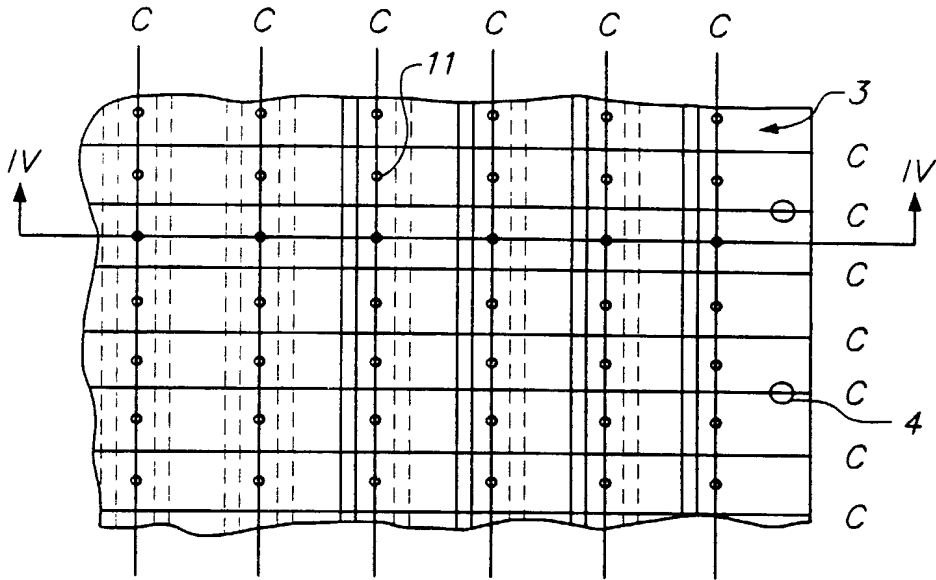


FIG. 3

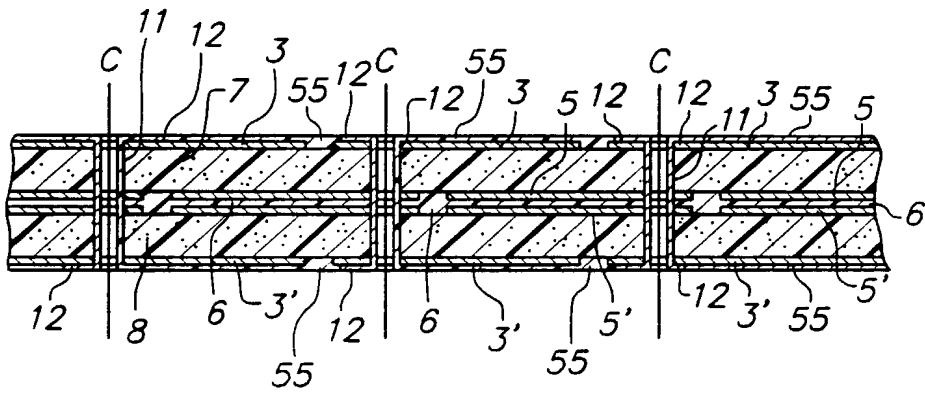


FIG. 4

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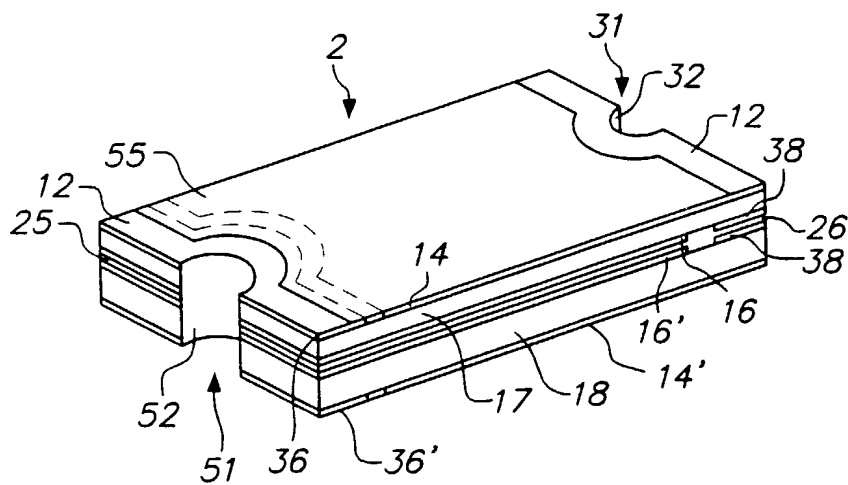


FIG. 5

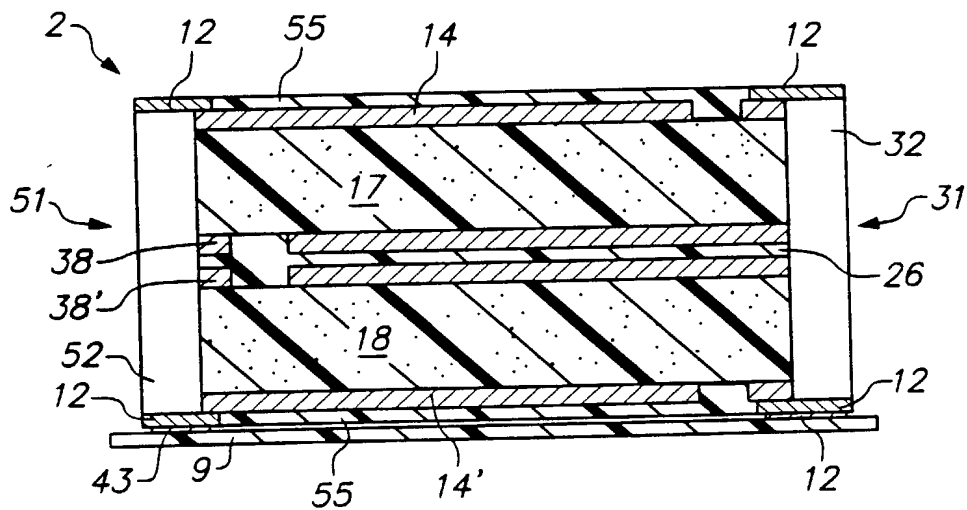


FIG. 6

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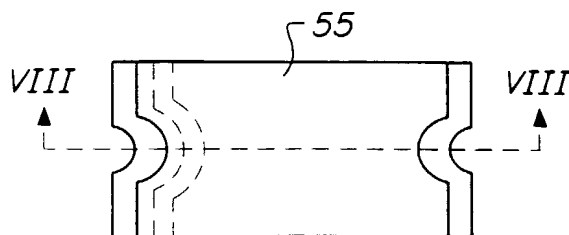


FIG. 7

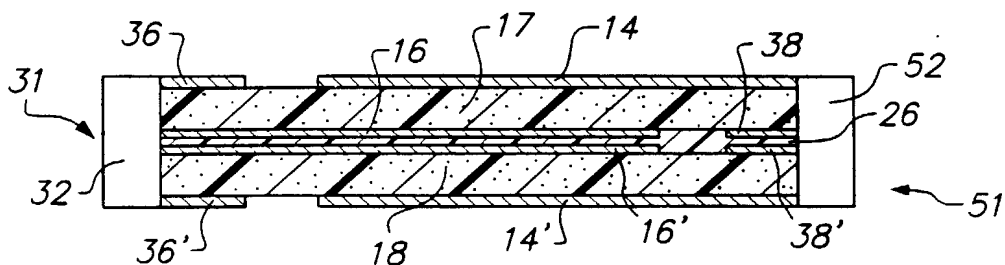


FIG. 8

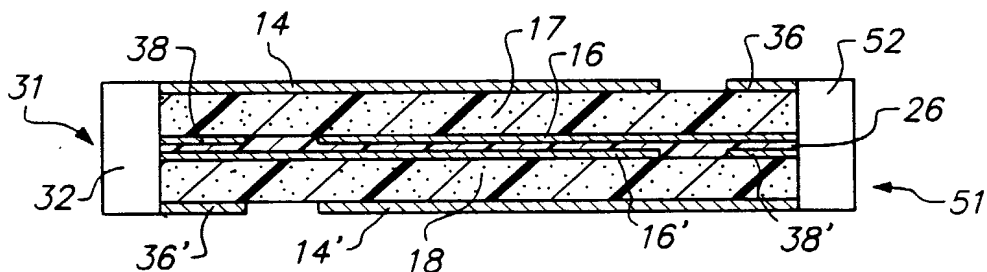


FIG. 9

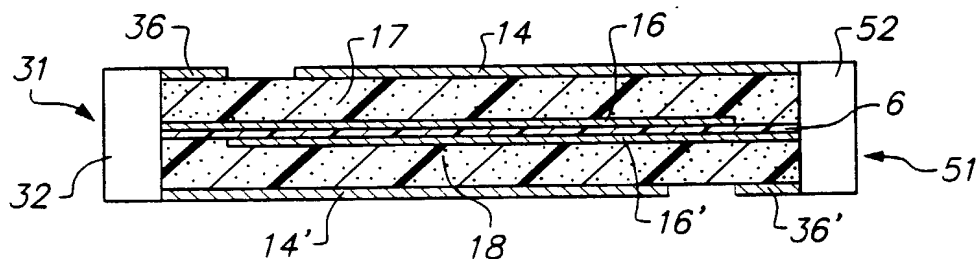
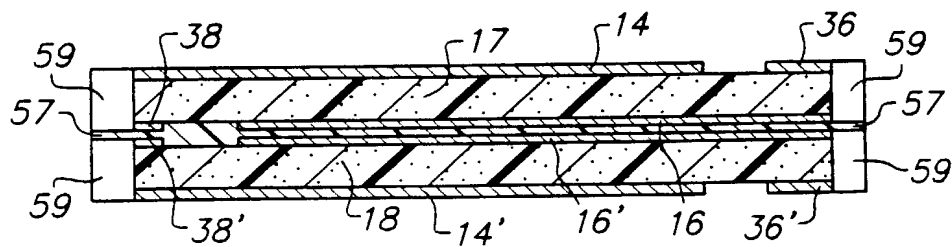
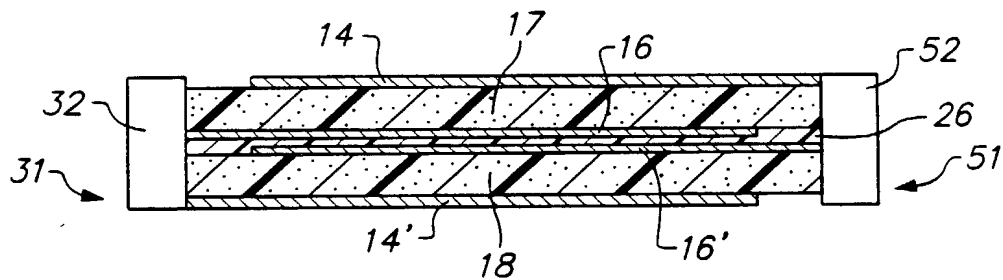
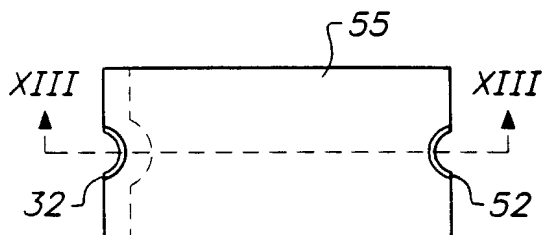
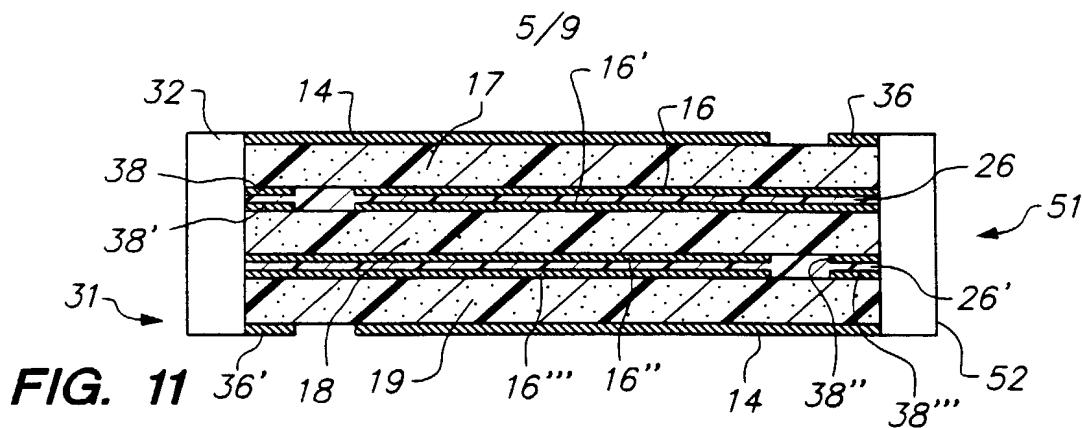
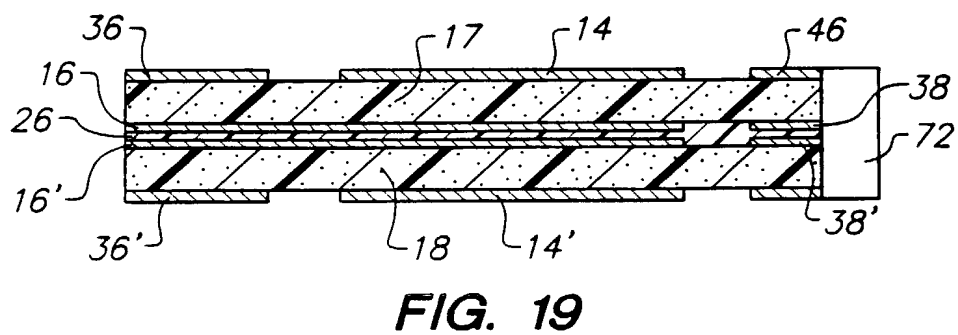
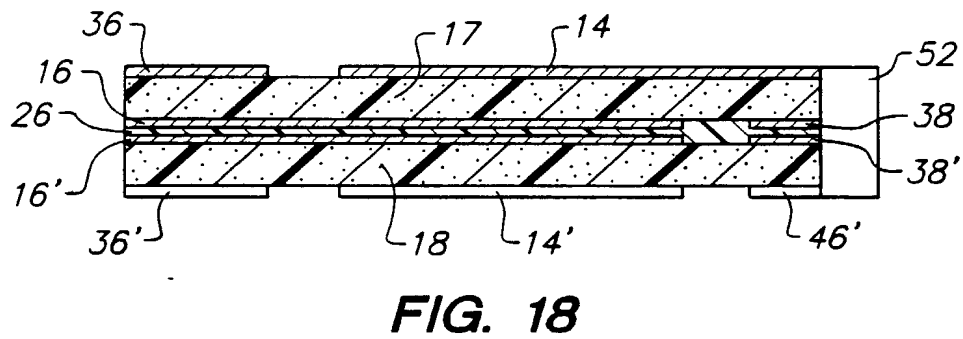
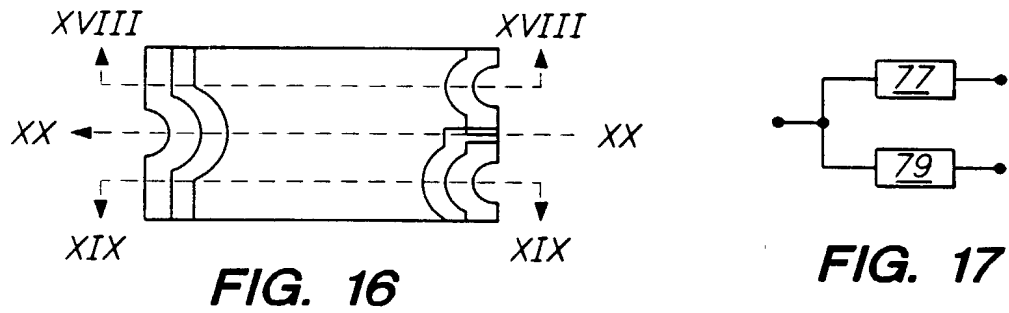
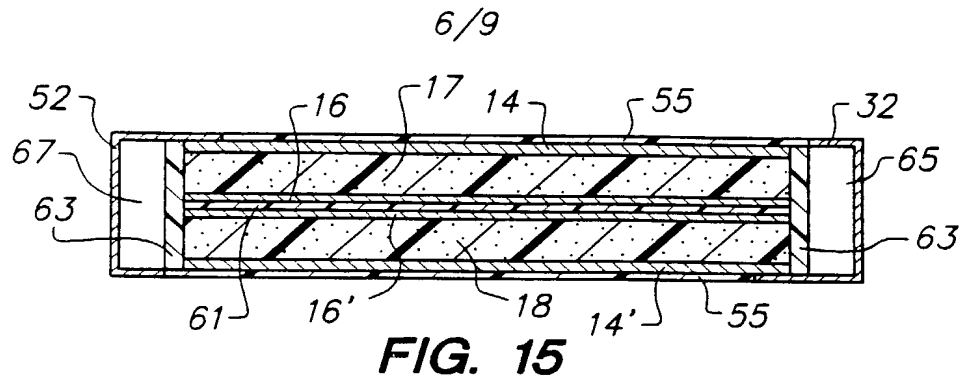


FIG. 10





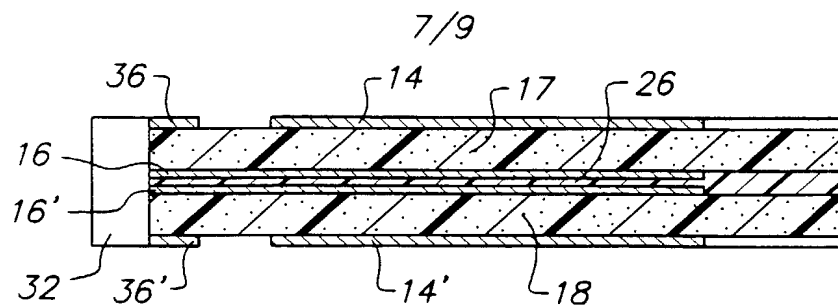


FIG. 20

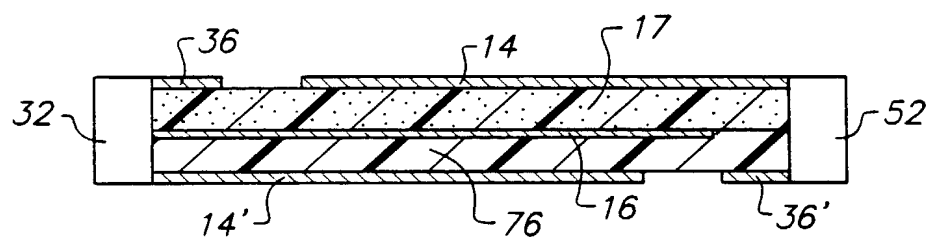


FIG. 21

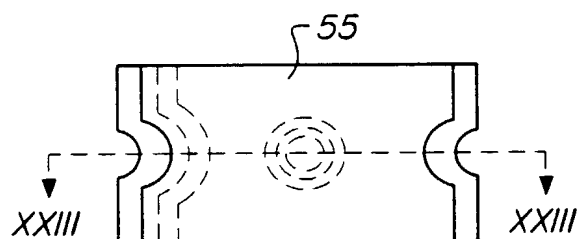


FIG. 22

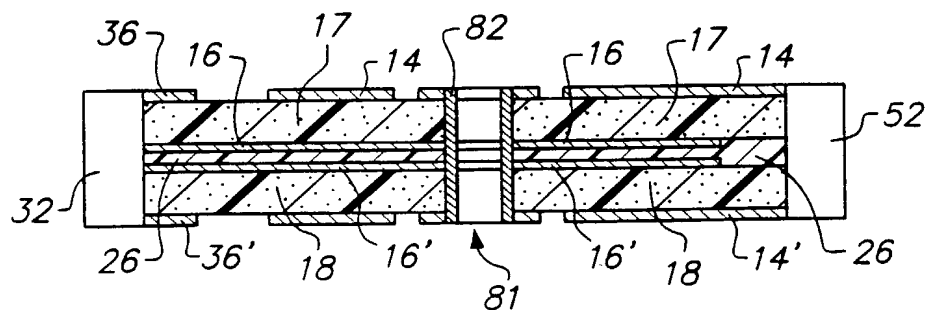


FIG. 23

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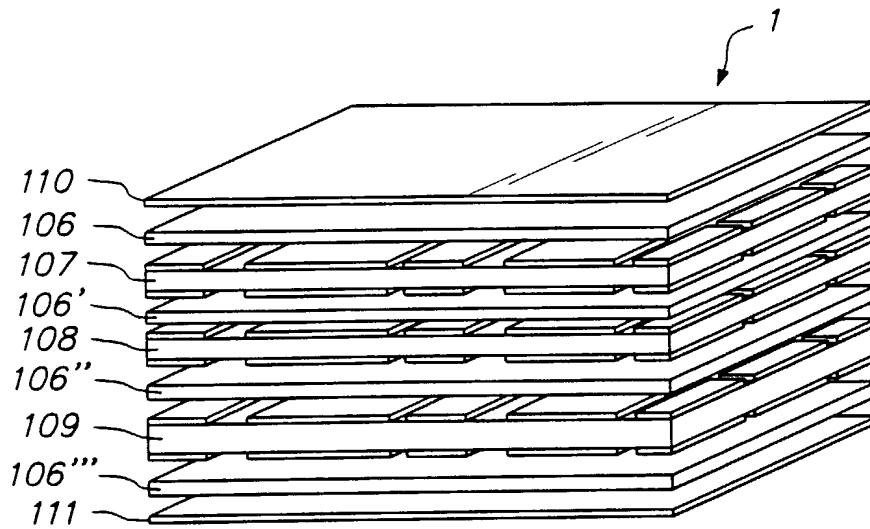


FIG. 24

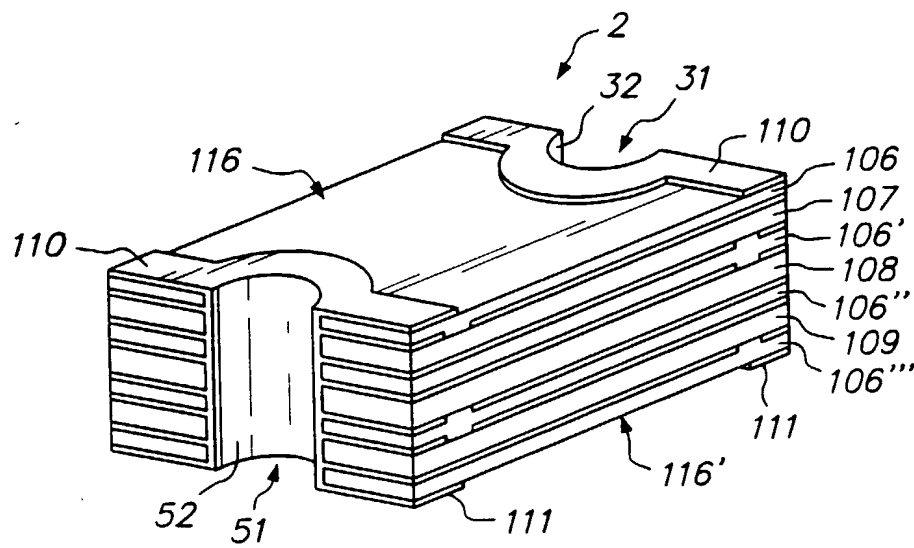


FIG. 25

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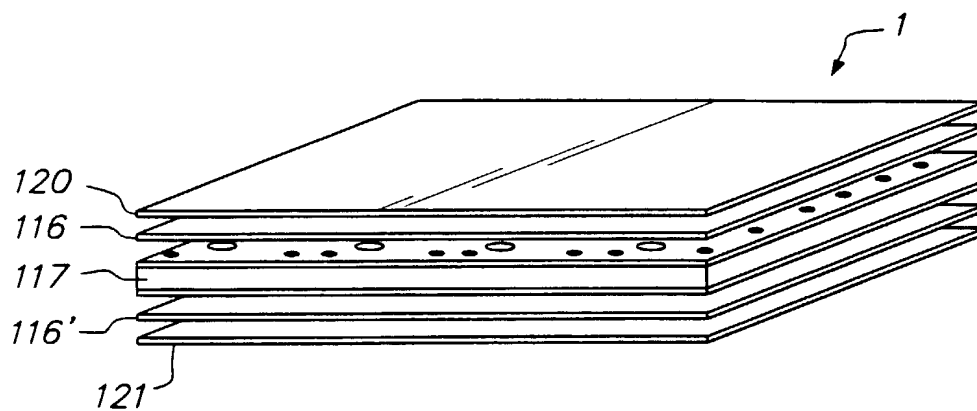


FIG. 26

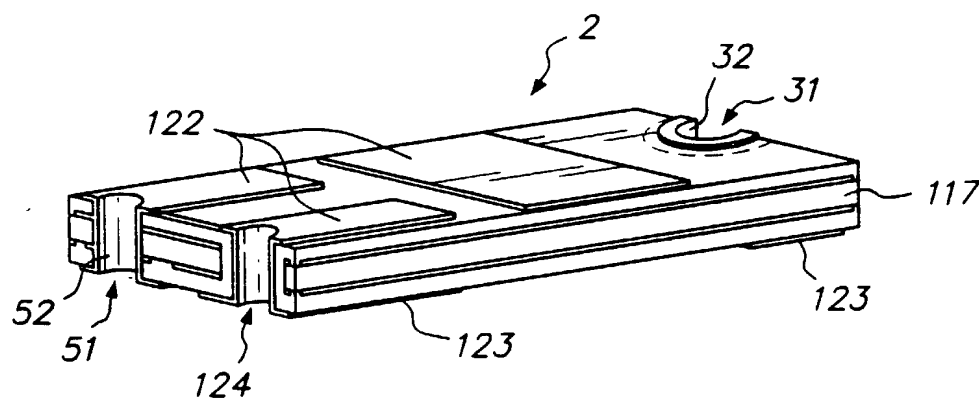


FIG. 27

DECLARATION FOR PATENT APPLICATION

As a below named inventor, I hereby declare that:

Docket Number

MP1705-US3

My residence, post office address, and citizenship are stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

ELECTRICAL DEVICES AND PROCESS FOR MAKING SUCH DEVICES

the specification of which is attached hereto unless the following box is checked:

☒ was filed on March 14, 2002 as United States Application Number or PCT International Application Number 10/088,253 and was amended on _____ (if applicable).

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, §1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, §119(a)-(d) of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed.

Prior Foreign Application(s)

Priority Claimed

_____ (Number)	_____ (Country)	_____ (Day/Month/Year Filed)	<input type="checkbox"/> Yes	<input type="checkbox"/> No
_____ (Number)	_____ (Country)	_____ (Day/Month/Year Filed)	<input type="checkbox"/> Yes	<input type="checkbox"/> No
_____ (Number)	_____ (Country)	_____ (Day/Month/Year Filed)	<input type="checkbox"/> Yes	<input type="checkbox"/> No
_____ (Number)	_____ (Country)	_____ (Day/Month/Year Filed)	<input type="checkbox"/> Yes	<input type="checkbox"/> No

I hereby claim the benefit under Title 35, United States Code, §119(e) of any United States provisional applications listed below.

_____ (Application Number)	_____ (Filing Date)
_____ (Application Number)	_____ (Filing Date)
_____ (Application Number)	_____ (Filing Date)
_____ (Application Number)	_____ (Filing Date)

I hereby claim the benefit under Title 35, United States Code, §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, §1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application.

<u>09/395,869</u> (Application Number)	<u>September 14, 1999</u> (Filing Date)	<u>pending</u> (Status — patented, pending, abandoned)
<u>PCT/US00/25118</u> (Application Number)	<u>September 13, 2000</u> (Filing Date)	<u>pending</u> (Status — patented, pending, abandoned)
_____ (Application Number)	_____ (Filing Date)	_____ (Status — patented, pending, abandoned)
_____ (Application Number)	_____ (Filing Date)	_____ (Status — patented, pending, abandoned)

DECLARATION FOR PATENT APPLICATION (continued)

Docket Number
MP1705-US3

I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

Marguerite E. Gerstner (Reg. No. 32,695)

Sheri M. Novack (Reg. No. 32,526)

Michael J. Aronoff (Reg. No. 37,770)

Address all telephone calls to
and all correspondence to the same at

Marguerite E. Gerstner, telephone 650-361-2483
Tyco Electronics Corporation
Intellectual Property Law Dept.
307 Constitution Drive, MS R20/2B
Menlo Park, CA 94025-1164

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true, and further that these statements are made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of sole or first inventor (given name, family name)

Scott Hetherton

Inventor's signature

Date

Citizenship

United States of America

Residence

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Post Office Address

Same as above

Full name of second joint inventor, if any (given name, family name)

Wayne Montoya

Inventor's signature

Date

Citizenship

United States of America

Residence

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Post Office Address

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Full name of third joint inventor, if any (given name, family name)

Thomas Bruguier

Inventor's signature

Date

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Residence

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Post Office Address

Same as above

Full name of fourth joint inventor, if any (given name, family name)

Randy Daering

Inventor's signature

Date

Citizenship

United States of America

Residence

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Post Office Address

Same as above

Full name of fifth joint inventor, if any (given name, family name)

Inventor's signature

Date

Citizenship

Residence

Post Office Address

Same as above

☐ Additional inventors are being named on separately numbered sheets attached hereto.

☐ Additional application(s) under which priority benefits are claimed under 35 USC §§119(a)-(d), 119(e) and/or 120 are identified on a sheet attached hereto.

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☐ Yes ☐ No

☐ Yes ☐ No

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(Application Number)

(Filing Date)

(Application Number)

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(Filing Date)

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09/395,869

(Application Number)

PCT/US00/25118

(Application Number)

(Application Number)

(Application Number)

September 14, 1999

(Filing Date)

September 13, 2000

(Filing Date)

(Filing Date)

(Filing Date)

pending

(Status — patented, pending, abandoned)

pending

(Status — patented, pending, abandoned)

(Status — patented, pending, abandoned)

(Status — patented, pending, abandoned)

DECLARATION FOR PATENT APPLICATION (continued)

Docket Number

MP1705-US3

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Scott Hetherton

Inventor's signature

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_____ (Application Number)	_____ (Filing Date)	(Status — patented, pending, abandoned)
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DECLARATION FOR PATENT APPLICATION (continued)

Docket Number MP1705-US3

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Full name of sole or first inventor (given name, family name) **Scott Hetherton**

Inventor's signature _____

Date _____

Citizenship **United States of America**

Residence **N1W33578 Abitz Road, Oconomowoc, Wisconsin 53066, United States of America**

Post Office Address **Same as above**

Full name of second joint inventor, if any (given name, family name) **Wayne Montoya**

Inventor's signature *Wayne Montoya*

Date **7-29-02**

Citizenship **United States of America**

Residence **544 Palomar Drive, Redwood City, California 94062-3231, United States of America**

Post Office Address **Same as above** *CA*

Full name of third joint inventor, if any (given name, family name) **Thomas Bruguier**

Inventor's signature _____

Date _____

Citizenship **United States of America**

Residence **7547 Trotter Way, Pleasanton, California 94566, United States of America**

Post Office Address **Same as above**

Full name of fourth joint inventor, if any (given name, family name) **Randy Daering**

Inventor's signature _____

Date _____

Citizenship **United States of America**

Residence **S44W32831 Rhapsody Lane, Waukesha, Wisconsin 53189 United States of America**

Post Office Address **Same as above**

Full name of fifth joint inventor, if any (given name, family name) _____

Inventor's signature _____

Date _____

Citizenship _____

Residence _____

Post Office Address **Same as above**

- ☐ Additional inventors are being named on separately numbered sheets attached hereto.
- ☐ Additional application(s) under which priority benefits are claimed under 35 USC §§119(a)-(d), 119(e) and/or 120 are identified on a sheet attached hereto.